

## Claims

What is claimed is:

- 5 1. A light emitting diode (LED) package structure, comprising:  
a substrate;  
a light emitting diode die located on the substrate; and  
a phosphoric medium layer located on the substrate and covered  
the light emitting diode die, wherein the phosphoric  
10 medium layer comprises a package mold precipitated a  
phosphor sediment layer on bottom and the phosphor  
sediment layer tightly covers the light emitting diode die.
- 15 2. The LED package structure of claim 1 wherein the package  
mold is an epoxy resin.
3. The LED package structure of claim 1 wherein the phosphor  
sediment layer is composed of phosphor powders.
- 20 4. The LED package structure of claim 1 wherein the phosphoric  
medium layer is formed on the substrate by a casting mold.
5. The LED package structure of claim 1 emits white light.
- 25 6. The LED package structure of claim 1 wherein the phosphoric

medium layer further covered by an outer package mold.

7. The LED package structure of claim 6 wherein the outer package mold is formed on the substrate by a casting mold.

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8. The LED package structure of claim 6 wherein the outer package mold is an epoxy resin.

9. The LED package structure of claim 1 wherein the substrate is a printed circuit board.
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